

IN THE ABSTRACT

Please replace the Abstract with the following:

In one aspect, the present invention relates to a method of manufacturing an integrated circuit package, the method including installing a carrier onto a substrate, attaching a semiconductor die to the substrate, and aligning an assembly over the semiconductor die, wherein the assembly includes a heat sink and a thermally conductive element. This aspect further includes resting the assembly on the carrier such that the thermally conductive element does not directly contact the semiconductor die, and encapsulating the thermally conductive element and the heat sink such that a portion of the heat sink is exposed to the surroundings of the package.